

Product Change Notification - LIAL-01RQFV346

Date:

08 Jun 2020

Product Category:

HV Amplifier Arrays for MEMS and Piezo Drive

Affected CPNs:

Notification subject:

CCB 3745.001 Final Notice: Qualification of UNIS as an additional assembly site for selected HV264 and HV265 device families available in 24L TSSOP (4.4mm) package

Notification text:
PCN Status:

Final notification.

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of UNIS as an additional assembly site for selected HV264 and HV265 device families available in 24L TSSOP (4.4mm) package.

Pre Change:

Assembled at CARM using 84-1KMISR4 die attach and EME-G700L mold compound material

Post Change:

Assembled at CARM using 84-1KMISR4 die attach and EME-G700L mold compound material or assembled at UNIS using 8290 die attach and G700HC mold compound material.

Pre and Post Change Summary:

	Pre Change		Post Change	
Assembly Site	Carsem (M) SDN BHD (CARM)	Carsem (M) SDN BHD (CARM)	Unisem (M) Berhad Perak, Malaysia (UNIS)	
Wire material	Au	Au	Au	
Die attach material	84-1KMISR4	84-1KMISR4	8290	
Molding compound material	EME-G700L	EME-G700L	G700HC	
Lead frame material	C7025	C7025	C7025	

Impacts to Data Sheet:



None

Change Impact:

None

Reason for Change:

To improve manufacturability and on-time delivery performance by qualifying UNIS as an additional assembly

Change Implementation Status:

In Progress

Estimated First Ship Date:

August 1, 2020 (date code: 2031)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Workweek	June 2020					-->	August 2020				
	23	24	25	26	27		31	32	33	34	35
Final PCN Issue Date		X									
Qual Report Availability		X									
Estimated Implementation Date							X				

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

June 8, 2020: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on August 1, 2020

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_LIAL-01RQFV346_QUAL_REPORT.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to [receive Microchip PCNs via email](#) please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about



registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

HV264TS-G

HV265-I/QE